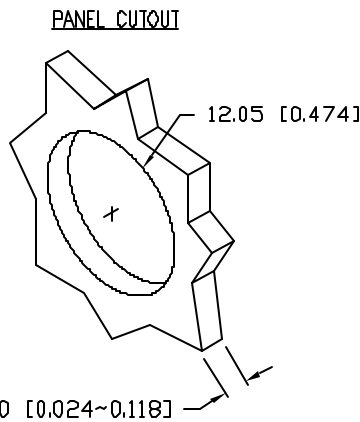
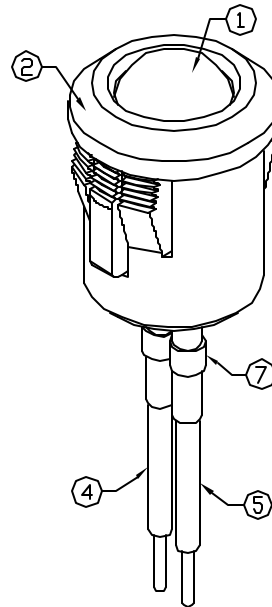
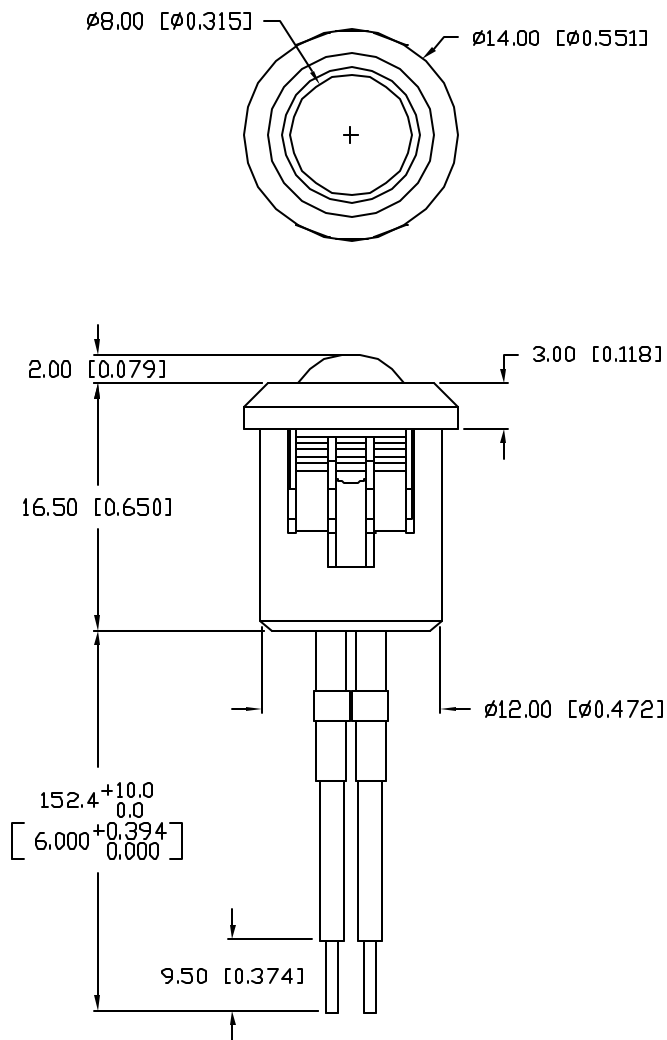


CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		470		nm	
FORWARD VOLTAGE		3.5	4.0	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		250		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	BLUE				
EPOXY LENS FINISH:	BLUE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	98	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$

* $t < 10\mu\text{s}$

NOTES:

1. SSI-LX80113USBD, BLUE LED.
2. SSH-RTF8080, BLACK HOLDER.
3. ANODE LEAD: LXP-WST24RDTC, 24 AWG STRANDED, RED INSULATION, CUT 150mm LONG, STRIP 3mm & 9.5mm.
4. CATHODE LEAD: LXP-WST24BLTC, 24 AWG STRANDED, BLACK INSULATION, CUT 150mm LONG, STRIP 3mm & 9.5mm.
5. CRIMP WIRE LEADS TO LED LEADS.
6. UV EPOXY TO RETAIN LED IN HOLDER.
7. 2 PCS. - 32mm, 1/16" BLACK HEATSHRINK TUBING.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+0.00}/_{-0.00} DECIMAL PRECISION, MAX= ^{+0.00}/_{-0.00} DECIMAL PRECISION

REV.	PART NUMBER SSI-LXH8080USBD150	CONFIDENTIAL INFORMATION THE INFORMATION CONTAINED IN THIS DOCUMENT IS THE PROPERTY OF LUMEX INC. EXCEPT AS SPECIFICALLY AUTHORIZED IN WRITING BY LUMEX INC, THE HOLDER OF THIS DOCUMENT SHALL KEEP ALL INFORMATION CONTAINED HEREIN CONFIDENTIAL AND SHALL PROTECT SAME IN WHOLE OR IN PART FROM DISCLOSURE AND DISSEMINATION TO ALL THIRD PARTIES.	290 E. HELEN ROAD PALATINE, IL 60067-6976 PHONE: +1.847.359.2790 US WEB: www.lumex.com TW WEB: www.lumex.com.tw
T-8mm 470nm InGaN/SiC BLUE PANEL INDICATOR LED, BLUE DIFFUSED LED, 6" WIRE LEADS.		RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.	DRAWN BY: BC CHECKED BY: APPROVED BY: DATE: 1.8.02 PAGE: 1 OF 1 SCALE: N/A